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(71) Applicant:

SAMSUNG ELECTRONICS CO., LTD.

(72) Inventor:

CHO, GANG SIK

CHO, HU SEONG

HWANG, DEOK SEONG

KIM, GYU CHEOL

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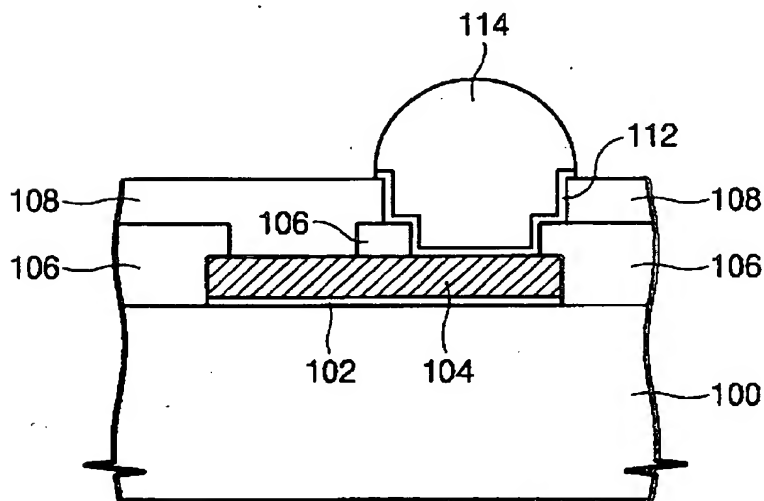
FLIP CHIP PAD AND FABRICATING METHOD THEREOF

Representative drawing

(57) Abstract:

PURPOSE: A flip chip pad is provided to improve a contact characteristic of a bump and a pad by forming the bump in a region not damaged in a process of testing an electrical characteristic, and to increase packaging reliability by forming the bump of an excellent structure.

CONSTITUTION: The pad(104) is disposed in a predetermined region of a semiconductor substrate(100), including a bump region and a probe region. The front surface of the semiconductor substrate is covered with an insulation layer. The bump(114) penetrates the insulation layer to be connected to the bump region, protruding over the insulation layer.



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